

# BZX84J series

## Single Zener diodes

Rev. 2 — 1 August 2011 Product data sheet

## 1. Product profile

### 1.1 General description

General-purpose Zener diodes in a SOD323F (SC-90) very small and flat lead Surface-Mounted Device (SMD) plastic package.

### 1.2 Features and benefits

- Non-repetitive peak reverse power dissipation: ≤ 40 W
- Total power dissipation: ≤ 550 mW
- AEC-Q101 qualified
- Small plastic package suitable for surface-mounted design
- Wide working voltage range: nominal 2.4 V to 75 V (E24 range)
- Two tolerance series: ±2 % and ±5 %
- Low differential resistance

### 1.3 Applications

- General regulation functions

### 1.4 Quick reference data

**Table 1. Quick reference data**

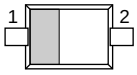
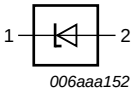
| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_F$ | forward voltage | $I_F$ = 100 mA | [1] | - | - | 1.1 | V |
| $P_{ZSM}$ | non-repetitive peak reverse power dissipation | | [2] | - | - | 40 | W |

[1] Pulse test: $t_p \leq 300\ \mu s$; $\delta \leq 0.02$.

[2] $t_p$ = 100 μs; square wave; $T_j$ = 25 °C prior to surge

## 2. Pinning information

**Table 2. Pinning**

| Pin | Description | | Simplified outline | Symbol |
|---|---|---|---|---|
| 1 | cathode | [1] |  |  |
| 2 | anode | | | |



[1] The marking bar indicates the cathode.

## 3. Ordering information

**Table 3. Ordering information**

| Type number | Package | | |
|---|---|---|---|
| | Name | Description | Version |
| BZX84J-B2V4 to BZX84J-C75[1] | SC-90 | plastic surface-mounted package; 2 leads | SOD323F |

[1] The series consists of 74 types with nominal working voltages from 2.4 V to 75 V.

## 4. Marking

**Table 4. Marking codes**

| Type number | Marking code | Type number | Marking code | Type number | Marking code | Type number | Marking code |
|---|---|---|---|---|---|---|---|
| BZX84J-B2V4 | SL | BZX84J-B15 | SC | BZX84J-C2V4 | U3 | BZX84J-C15 | TV |
| BZX84J-B2V7 | SM | BZX84J-B16 | SD | BZX84J-C2V7 | U4 | BZX84J-C16 | TW |
| BZX84J-B3V0 | ST | BZX84J-B18 | SE | BZX84J-C3V0 | U9 | BZX84J-C18 | TX |
| BZX84J-B3V3 | SU | BZX84J-B20 | SF | BZX84J-C3V3 | UA | BZX84J-C20 | TY |
| BZX84J-B3V6 | SV | BZX84J-B22 | SG | BZX84J-C3V6 | UB | BZX84J-C22 | TZ |
| BZX84J-B3V9 | SW | BZX84J-B24 | SH | BZX84J-C3V9 | UC | BZX84J-C24 | U1 |
| BZX84J-B4V3 | SZ | BZX84J-B27 | SK | BZX84J-C4V3 | UF | BZX84J-C27 | U2 |
| BZX84J-B4V7 | TA | BZX84J-B30 | SN | BZX84J-C4V7 | UG | BZX84J-C30 | U5 |
| BZX84J-B5V1 | TD | BZX84J-B33 | SP | BZX84J-C5V1 | UL | BZX84J-C33 | U6 |
| BZX84J-B5V6 | TE | BZX84J-B36 | SR | BZX84J-C5V6 | UM | BZX84J-C36 | U7 |
| BZX84J-B6V2 | TH | BZX84J-B39 | SS | BZX84J-C6V2 | UR | BZX84J-C39 | U8 |
| BZX84J-B6V8 | TK | BZX84J-B43 | SX | BZX84J-C6V8 | US | BZX84J-C43 | UD |
| BZX84J-B7V5 | TM | BZX84J-B47 | SY | BZX84J-C7V5 | UU | BZX84J-C47 | UE |
| BZX84J-B8V2 | TN | BZX84J-B51 | TB | BZX84J-C8V2 | UV | BZX84J-C51 | UH |
| BZX84J-B9V1 | TP | BZX84J-B56 | TC | BZX84J-C9V1 | UW | BZX84J-C56 | UK |
| BZX84J-B10 | S8 | BZX84J-B62 | TF | BZX84J-C10 | TR | BZX84J-C62 | UN |
| BZX84J-B11 | S9 | BZX84J-B68 | TG | BZX84J-C11 | TS | BZX84J-C68 | UP |
| BZX84J-B12 | SA | BZX84J-B75 | TL | BZX84J-C12 | TT | BZX84J-C75 | UT |
| BZX84J-B13 | SB | - | - | BZX84J-C13 | TU | - | - |


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## 5. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---|---|---|---|---|---|---|
| $I_F$ | forward current | | | - | 250 | mA |
| $I_{ZSM}$ | non-repetitive peak reverse current | | [1] | - | see Table 8 and 9 | |
| $P_{ZSM}$ | non-repetitive peak reverse power dissipation | | [1] | - | 40 | W |
| $P_{tot}$ | total power dissipation | $T_{amb} \leq 25$ °C | [2] | - | 550 | mW |
| $T_j$ | junction temperature | | | - | 150 | °C |
| $T_{amb}$ | ambient temperature | | | −55 | +150 | °C |
| $T_{stg}$ | storage temperature | | | −65 | +150 | °C |

[1] $t_p = 100$ µs; square wave; $T_j = 25$ °C prior to surge

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 $cm^2$.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | - | 230 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [2] | - | - | 55 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 $cm^2$.

[2] Soldering point of cathode tab.

## 7. Characteristics

**Table 7. Characteristics**

*$T_j$ = 25 °C unless otherwise specified.*

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_F$ | forward voltage | | [1] | | | | |
| | | $I_F$ = 10 mA | | - | - | 0.9 | V |
| | | $I_F$ = 100 mA | | - | - | 1.1 | V |

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.


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**Table 8. Characteristics per type; BZX84J-B2V4 to BZX84J-C24**

*$T_j$ = 25 °C unless otherwise specified.*

| BZX84J-xxx | Sel | Working voltage $V_Z$ (V) | | Differential resistance $r_{dif}$ (Ω) | | Reverse current $I_R$ (μA) | | Temperature coefficient $S_Z$ (mV/K) | | Diode capacitance $C_d$ (pF)[1] | Non-repetitive peak reverse current $I_{ZSM}$ (A)[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | $I_Z$ = 5 mA | | $I_Z$ = 1 mA | $I_Z$ = 5 mA | | | $I_Z$ = 5 mA | | | |
| | | Min | Max | Max | Max | Max | $V_R$ (V) | Min | Max | Max | Max |
| 2V4 | B | 2.35 | 2.45 | 400 | 100 | 50 | 1 | −3.5 | 0 | 450 | 12 |
| | C | 2.2 | 2.6 | | | | | | | | |
| 2V7 | B | 2.65 | 2.75 | 450 | 100 | 20 | 1 | −3.5 | 0 | 440 | 12 |
| | C | 2.5 | 2.9 | | | | | | | | |
| 3V0 | B | 2.94 | 3.06 | 500 | 95 | 10 | 1 | −3.5 | 0 | 425 | 12 |
| | C | 2.8 | 3.2 | | | | | | | | |
| 3V3 | B | 3.23 | 3.37 | 500 | 95 | 5 | 1 | −3.5 | 0 | 410 | 12 |
| | C | 3.1 | 3.5 | | | | | | | | |
| 3V6 | B | 3.53 | 3.67 | 500 | 90 | 5 | 1 | −3.5 | 0 | 390 | 12 |
| | C | 3.4 | 3.8 | | | | | | | | |
| 3V9 | B | 3.82 | 3.98 | 500 | 90 | 3 | 1 | −3.5 | 0 | 370 | 12 |
| | C | 3.7 | 4.1 | | | | | | | | |
| 4V3 | B | 4.21 | 4.39 | 600 | 90 | 3 | 1 | −3.5 | 0 | 350 | 12 |
| | C | 4 | 4.6 | | | | | | | | |
| 4V7 | B | 4.61 | 4.79 | 500 | 80 | 3 | 2 | −3.5 | 0.2 | 325 | 12 |
| | C | 4.4 | 5 | | | | | | | | |
| 5V1 | B | 5 | 5.2 | 480 | 60 | 2 | 2 | −2.7 | 1.2 | 300 | 12 |
| | C | 4.8 | 5.4 | | | | | | | | |
| 5V6 | B | 5.49 | 5.71 | 400 | 40 | 1 | 2 | −2 | 2.5 | 275 | 12 |
| | C | 5.2 | 6 | | | | | | | | |
| 6V2 | B | 6.08 | 6.32 | 150 | 10 | 3 | 4 | 0.4 | 3.7 | 250 | 12 |
| | C | 5.8 | 6.6 | | | | | | | | |
| 6V8 | B | 6.66 | 6.94 | 80 | 15 | 2 | 4 | 1.2 | 4.5 | 215 | 12 |
| | C | 6.4 | 7.2 | | | | | | | | |
| 7V5 | B | 7.35 | 7.65 | 80 | 10 | 1 | 5 | 2.5 | 5.3 | 170 | 4 |
| | C | 7 | 7.9 | | | | | | | | |
| 8V2 | B | 8.04 | 8.36 | 80 | 10 | 0.7 | 5 | 3.2 | 6.2 | 150 | 4 |
| | C | 7.7 | 8.7 | | | | | | | | |
| 9V1 | B | 8.92 | 9.28 | 100 | 10 | 0.5 | 6 | 3.8 | 7 | 120 | 3 |
| | C | 8.5 | 9.6 | | | | | | | | |
| 10 | B | 9.8 | 10.2 | 150 | 10 | 0.2 | 7 | 4.5 | 8 | 110 | 3 |
| | C | 9.4 | 10.6 | | | | | | | | |
| 11 | B | 10.8 | 11.2 | 150 | 10 | 0.1 | 8 | 5.4 | 9 | 108 | 2.5 |
| | C | 10.4 | 11.6 | | | | | | | | |
| 12 | B | 11.8 | 12.2 | 150 | 10 | 0.1 | 8 | 6 | 10 | 105 | 2.5 |
| | C | 11.4 | 12.7 | | | | | | | | |


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**Table 8. Characteristics per type; BZX84J-B2V4 to BZX84J-C24** *…continued*

*$T_j$ = 25 °C unless otherwise specified.*

| BZX84J-xxx | Sel | Working voltage $V_Z$ (V) | | Differential resistance $r_{dif}$ (Ω) | | Reverse current $I_R$ (μA) | | Temperature coefficient $S_Z$ (mV/K) | | Diode capacitance $C_d$ (pF)[1] | Non-repetitive peak reverse current $I_{ZSM}$ (A)[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | $I_Z$ = 5 mA | | $I_Z$ = 1 mA | $I_Z$ = 5 mA | | | $I_Z$ = 5 mA | | | |
| | | Min | Max | Max | Max | Max | $V_R$ (V) | Min | Max | Max | Max |
| 13 | B | 12.7 | 13.3 | 170 | 10 | 0.1 | 8 | 7 | 11 | 103 | 2.5 |
| | C | 12.4 | 14.1 | | | | | | | | |
| 15 | B | 14.7 | 15.3 | 200 | 15 | 0.05 | 10.5 | 9.2 | 13 | 99 | 2 |
| | C | 13.8 | 15.6 | | | | | | | | |
| 16 | B | 15.7 | 16.3 | 200 | 20 | 0.05 | 11.2 | 10.4 | 14 | 97 | 1.5 |
| | C | 15.3 | 17.1 | | | | | | | | |
| 18 | B | 17.6 | 18.4 | 225 | 20 | 0.05 | 12.6 | 12.4 | 16 | 93 | 1.5 |
| | C | 16.8 | 19.1 | | | | | | | | |
| 20 | B | 19.6 | 20.4 | 225 | 20 | 0.05 | 14 | 14.4 | 18 | 88 | 1.5 |
| | C | 18.8 | 21.2 | | | | | | | | |
| 22 | B | 21.6 | 22.4 | 250 | 25 | 0.05 | 15.4 | 16.4 | 20 | 84 | 1.25 |
| | C | 20.8 | 23.3 | | | | | | | | |
| 24 | B | 23.5 | 24.5 | 250 | 30 | 0.05 | 16.8 | 18.4 | 22 | 80 | 1.25 |
| | C | 22.8 | 25.6 | | | | | | | | |

[1] f = 1 MHz; $V_R$ = 0 V

[2] $t_p$ = 100 μs; square wave; $T_j$ = 25 °C prior to surge


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**Table 9. Characteristics per type; BZX84J-B27 to BZX84J-C75**

*$T_j$ = 25 °C unless otherwise specified.*

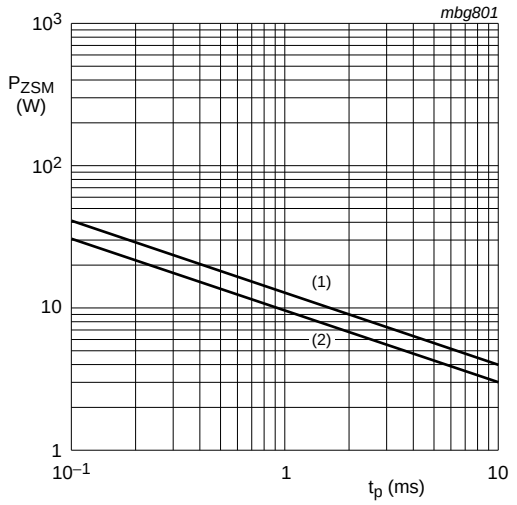
| BZX84J-xxx | Sel | Working voltage $V_Z$ (V) | | Differential resistance $r_{dif}$ (Ω) | | Reverse current $I_R$ (μA) | | Temperature coefficient $S_Z$ (mV/K) | | Diode capacitance $C_d$ (pF)[1] | Non-repetitive peak reverse current $I_{ZSM}$ (A)[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | $I_Z$ = 2 mA | | $I_Z$ = 0.5 mA | $I_Z$ = 2 mA | | | $I_Z$ = 2 mA | | | |
| | | Min | Max | Max | Max | Max | $V_R$ (V) | Min | Max | Max | Max |
| 27 | B | 26.5 | 27.5 | 250 | 40 | 0.05 | 18.9 | 21.4 | 25.3 | 73 | 1 |
| | C | 25.1 | 28.9 | | | | | | | | |
| 30 | B | 29.4 | 30.6 | 250 | 40 | 0.05 | 21 | 24.4 | 29.4 | 66 | 1 |
| | C | 28 | 32 | | | | | | | | |
| 33 | B | 32.3 | 33.7 | 275 | 40 | 0.05 | 23.1 | 27.4 | 33.4 | 60 | 0.9 |
| | C | 31 | 35 | | | | | | | | |
| 36 | B | 35.3 | 36.7 | 300 | 60 | 0.05 | 25.2 | 30.4 | 37.4 | 59 | 0.8 |
| | C | 34 | 38 | | | | | | | | |
| 39 | B | 38.2 | 39.8 | 300 | 75 | 0.05 | 27.3 | 33.4 | 41.2 | 58 | 0.7 |
| | C | 37 | 41 | | | | | | | | |
| 43 | B | 42.1 | 43.9 | 325 | 80 | 0.05 | 30.1 | 37.6 | 46.6 | 56 | 0.6 |
| | C | 40 | 46 | | | | | | | | |
| 47 | B | 46.1 | 47.9 | 325 | 90 | 0.05 | 32.9 | 42 | 51.8 | 55 | 0.5 |
| | C | 44 | 50 | | | | | | | | |
| 51 | B | 50 | 52 | 350 | 110 | 0.05 | 35.7 | 46.6 | 57.2 | 52 | 0.4 |
| | C | 48 | 54 | | | | | | | | |
| 56 | B | 54.9 | 57.1 | 375 | 120 | 0.05 | 39.2 | 52.2 | 63.8 | 49 | 0.3 |
| | C | 52 | 60 | | | | | | | | |
| 62 | B | 60.8 | 63.2 | 400 | 140 | 0.05 | 43.4 | 58.8 | 71.6 | 44 | 0.3 |
| | C | 58 | 66 | | | | | | | | |
| 68 | B | 66.6 | 69.4 | 400 | 160 | 0.05 | 47.6 | 65.6 | 79.8 | 40 | 0.25 |
| | C | 64 | 72 | | | | | | | | |
| 75 | B | 73.5 | 76.5 | 400 | 175 | 0.05 | 52.5 | 73.4 | 88.6 | 35 | 0.2 |
| | C | 70 | 79 | | | | | | | | |

[1] f = 1 MHz; $V_R$ = 0 V

[2] $t_p$ = 100 μs; square wave; $T_j$ = 25 °C prior to surge


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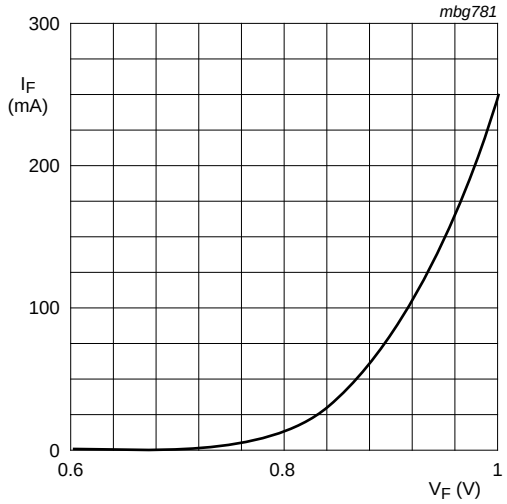
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(1) $T_j$ = 25 °C (prior to surge)

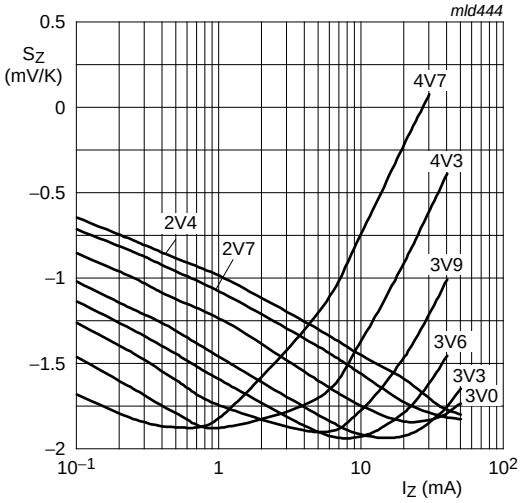
(2) $T_j$ = 150 °C (prior to surge)

**Fig 1. Non-repetitive peak reverse power dissipation as a function of pulse duration; maximum values**




$T_j$ = 25 °C

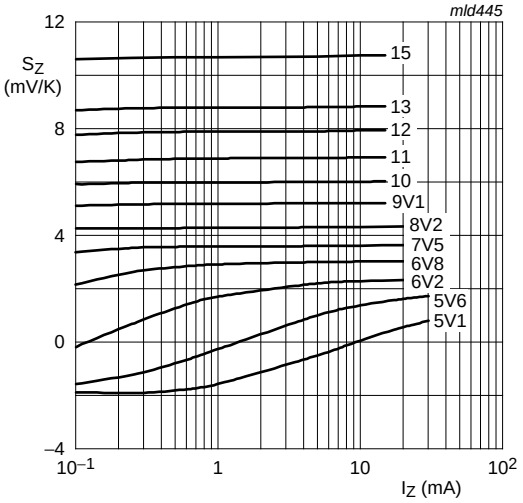
**Fig 2. Forward current as a function of forward voltage; typical values**




BZX84J-B/C2V4 to BZX84J-B/C4V7

$T_j$ = 25 °C to 150 °C

**Fig 3. Temperature coefficient as a function of working current; typical values**



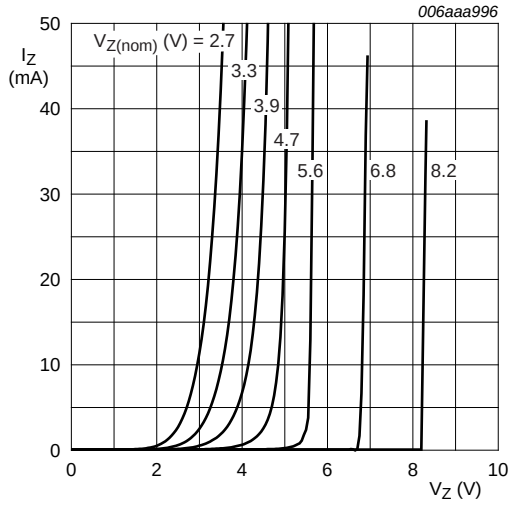

BZX84J-B/C5V1 to BZX84J-B/C15

$T_j$ = 25 °C to 150 °C

**Fig 4. Temperature coefficient as a function of working current; typical values**


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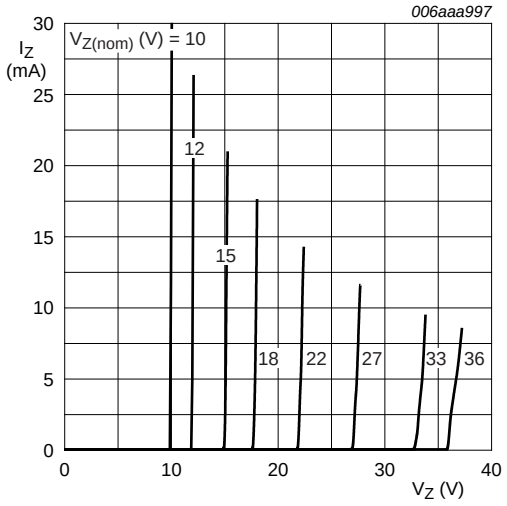
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$T_j$ = 25 °C

BZX84J-B/C2V7 to BZX84J-B/C8V2

**Fig 5. Working current as a function of working voltage; typical values**




$T_j$ = 25 °C

BZX84J-B/C10 to BZX84J-B/C36

**Fig 6. Working current as a function of working voltage; typical values**

# 8. Test information

## 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.


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## 9. Package outline

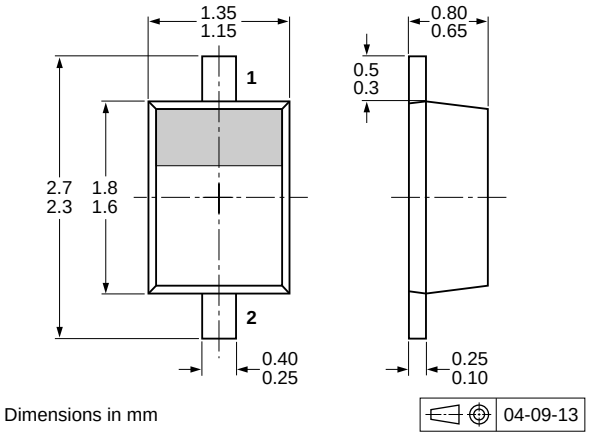



**Fig 7. Package outline SOD323F (SC-90)**

## 10. Packing information

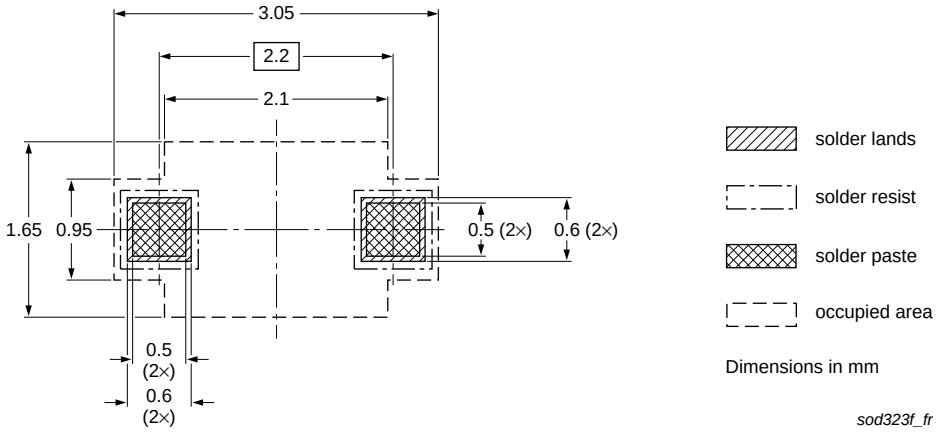
**Table 10. Packing methods**

*The indicated -xxx are the last three digits of the 12NC ordering code.*[1]

| Type number | Package | Description | Packing quantity | |
|---|---|---|---|---|
| | | | 3000 | 10000 |
| BZX84J-B2V4 to BZX84J-C75 | SOD323F | 4 mm pitch, 8 mm tape and reel | -115 | -135 |

[1] For further information and the availability of packing methods, see Section 14.

## 11. Soldering




Reflow soldering is the only recommended soldering method.

**Fig 8. Reflow soldering footprint SOD323F (SC-90)**


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## 12. Revision history

**Table 11. Revision history**

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---|---|---|---|---|
| BZX84J_SER v.2 | 20110801 | Product data sheet | - | BZX84J_SER v.1 |
| Modifications: | • Figure 5 and Figure 6 updated<br>• Figure 8 updated<br>• Section 1.2 “Features and benefits” updated<br>• Section 5 “Limiting values” updated<br>• Section 8 “Test information” added<br>• Section 13 “Legal information” updated | | | |
| BZX84J_SER v.1 | 20070301 | Product data sheet | - | - |


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# 13. Legal information

## 13.1 Data sheet status

| Document status[1][2] | Product status[3] | Definition |
|---|---|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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## 14. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**


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## 15. Contents


**1 Product profile . . . . . 1**
1.1 General description . . . . . 1
1.2 Features and benefits . . . . . 1
1.3 Applications . . . . . 1
1.4 Quick reference data . . . . . 1
**2 Pinning information . . . . . 1**
**3 Ordering information . . . . . 2**
**4 Marking . . . . . 2**
**5 Limiting values . . . . . 3**
**6 Thermal characteristics . . . . . 3**
**7 Characteristics . . . . . 3**
**8 Test information . . . . . 8**
8.1 Quality information . . . . . 8
**9 Package outline . . . . . 9**
**10 Packing information . . . . . 9**
**11 Soldering . . . . . 9**
**12 Revision history . . . . . 10**
**13 Legal information . . . . . 11**
13.1 Data sheet status . . . . . 11
13.2 Definitions . . . . . 11
13.3 Disclaimers . . . . . 11
13.4 Trademarks . . . . . 12
**14 Contact information . . . . . 12**
**15 Contents . . . . . 13**


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